

3M™ Thermally Conductive Silicone Interface Pad 5519

Product Description

3M™ Thermally Conductive Silicone Interface Pad (TCSIP) 5519 is designed to provide a preferential heat transfer path between heat generating components and heat sinks, heat spreaders or other cooling devices. 3M TCSIP 5519 consists of a highly conformable and slightly tacky silicone elastomer sheet filled with thermally conductive ceramic particles, which helps provide enhanced thermal conductivity and excellent electrical insulation performance.

Key Features

- Very high thermal conductivity and good electrical insulation properties
- Good softness and conformability even to non-flat surfaces
- Good electrical insulation properties
- Good flame retardant, UL94 V-0 equivalent material
- Compression relaxation properties help reduce pressure to electric components
- Slight tack allows pre-assembly
- Good wettability for improved and lower thermal resistance

Product Construction/Material Description

The following technical information and data should be considered representative or typical only and should not be used for

one Interface Pad 5519 Value	
White	11 3
Silicone	
0.5 – 2.0mm*	
Ceramic	
PFT Film Liner	
	White Silicone 0.5 – 2.0mm*

^{*} Standard thickness range. Custom thickness options available up to 10mm. Contact your local 3M representative for more information.

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PET Liner	
Filled Silicone Elastomer	
PET Liner	

Applications

- Integrated chip (IC) packaging heat conduction
- Heat sink interface
- Chip on film (COF) heat conduction
- LED board thermal interface material (TIM)
- HDTV integrated chip (IC)
- General gap filling in electronic device

Precision Die-Cutting Hook & Loop Fasteners

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Application Techniques

Be sure to read and follow the manufacturers' precautions and directions when using solvents.

Substrate surfaces should be clean and dry prior to the thermal pad application to ensure best thermal performance. A clean surface can improve the thermal performance of an application.

- Isopropyl alcohol (isopropanol) applied with a lint-free wipe or swab should be adequate for removing surface contamination such as dust or fingerprints. Do not use "denatured alcohol" or glass cleaners, which often contain oily components. Allow the surface to dry for several minutes before applying the thermal pad. More aggressive solvents (such as acetone, methyl ethyl ketone (MEK) or toluene) may be required to remove heavier contamination (grease, machine oils, solder flux, etc.) but should be followed by a final isopropanol wipe as
- Apply the thermal pad to one substrate at a modest angle with the use of a squeegee, rubber roller or finger pressure to help reduce the potential for air entrapment under the thermal pad during its application.
- Remove the release liner before application.
- Assemble the part by applying compression to the substrates to ensure a good wetting of the substrate surfaces with the thermal pads. Rigid substrates are more difficult to assemble without air entrapment as most rigid parts are not flat. Flexible substrates can be assembled to rigid or flexible parts with much less concern about air entrapment because one of the flexible substrate can conform to the other substrates during application.

Typical Physical Properties and Performance Characteristics

The following technical information and data should be considered representative or typical only and should not be used for specification purposes. Final product specifications and testing methods will be outlined in the products Certificate of Analysis (COA) that is provided once the product is approved by 3M for general commercialization and development work is completed.

Method ^a	Value
	5 W/m-K
	3.1
	-50°C to 140°C
	70 ~ 80
Modified ASTM 02240	
UL94	V-0
Modified ASTM D149 (3M test method)	2 kV/mm
ASTM D257	1.7 x 10 ¹⁴ Ohms
	Modified ASTM D149 (3M test method)

^aMethods listed as ASTM are tested in accordance with the ASTM method noted

Storage and Shelf Life

The shelf life of 3M™ Thermally Conductive Silicone Interface Pads 5519 is 24 months from the date of manufacture when stored in the original packaging materials and stored at 21°C (70°F) and 50% relative humidity.

Certificate of Analysis (COA)

The 3M Certificate of Analysis (COA) for this product is established when the product is commercially available from 3M. The commercially available product will have a COA specification established. The COA contains the 3M specifications and test methods for the products performance limits that the product will be supplied against. The 3M product is supplied to 3M COA test specifications and the COA test methods. Contact your local 3M representative for this product's COA.

This technical data sheet may contain preliminary data and may not match the COA specification limits and/or test methods that may be used for COA purposes.

Final product specifications and testing methods will be outlined in the products Certificate of Analysis (COA) that is shipped with the commercialized product.

Shore 00 results depend on test method and thickness of the sample tested. Typical results are in the 60-80 Shore 00 range @ 6 mm test thickness without the PET film. Ask 3M for more details on pad softness.

[°]File QMZ2.E239181

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Safety Data Sheet: Consult Safety Data Sheet before use.

Regulatory: For regulatory information about this product, contact your 3M representative.

Technical Information: The technical information, recommendations and other statements contained in this document are based upon tests or experience that 3M believes are reliable, but the accuracy or completeness of such information is not guaranteed.

Product Use: Many factors beyond 3M's control and uniquely within user's knowledge and control can affect the use and performance of a 3M product in a particular application Given the variety of factors that can affect the use and performance of a 3M product, user is solely responsible for evaluating the 3M product and determining whether it is fit for a particular purpose and suitable for user's method of application.

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